

256K (32K x 8) Static RAM

Features

- High Speed
 - 70 ns
- Temperature Ranges

— Commercial: 0°C to 70°C - Industrial: -40°C to 85°C — Automotive: –40°C to 125°C

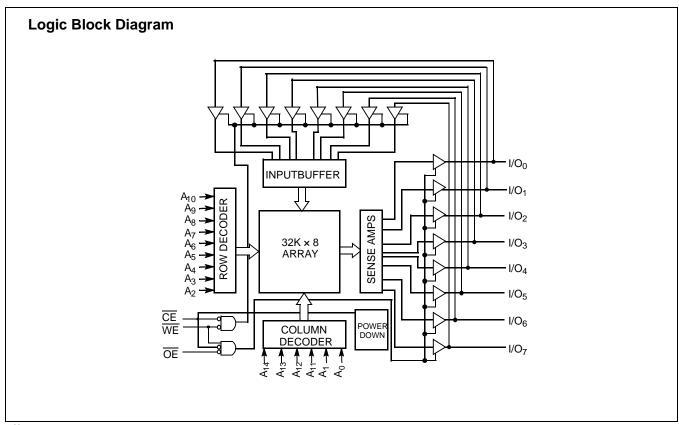
- · Low voltage range:
 - 2.7V 3.6V
- · Low active power and standby power
- Easy memory expansion with CE and OE features
- · TTL-compatible inputs and outputs
- Automatic power-down when deselected
- · CMOS for optimum speed/power
- Available in a Pb-free and non Pb-free standard 28-pin narrow SOIC, 28-pin TSOP-1 and 28-pin Reverse TSOP-1 packages

Functional Description[1]

The CY62256V family is composed of two high-performance CMOS static RAM's organized as 32K words by 8 bits. Easy memory expansion is provided by an active LOW chip enable (\overline{CE}) and active LOW output enable (\overline{OE}) and Tri-state drivers. These devices have an automatic power-down feature, reducing the power consumption by over 99% when deselected.

An active LOW write enable signal (WE) controls the writing/reading operation of the memory. When CE and WE inputs are both LOW, data on the eight data input/output pins (I/O₀ through I/O₇) is written into the memory location addressed by the address present on the address pins (A₀ through A₁₄). Reading the device is accomplished by selecting the device and enabling the outputs, CE and OE active LOW, while WE remains inactive or HIGH. Under these conditions, the contents of the location addressed by the information on address pins are present on the eight data input/output pins.

The input/output pins remain in a high-impedance state unless the chip is selected, outputs are enabled, and write enable (WE) is HIGH.



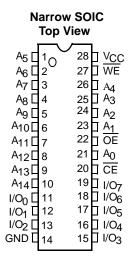
1. For best practice recommendations, please refer to the Cypress application note "System Design Guidelines" on http://www.cypress.com.

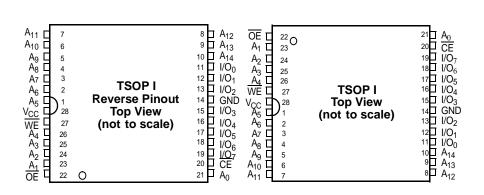


Product Portfolio

						Power Dissipation			
		Vo	_{CC} Range ((V)	Speed	Operating, I _{CC} (mA)		Standby, I _{SB2} (μA)	
Product	Range	Min.	Typ. ^[2]	Max.	(ns)	Typ. ^[2]	Max.	Typ. ^[2]	Max.
CY62256VLL	Com'l/Ind'l	2.7	3.0	3.6	70	11	30	0.1	5
	Automotive								130

Pin Configurations





Pin Definitions

Pin Number	Туре	Description
1–10, 21, 23–26	Input	A ₀ -A ₁₄ . Address Inputs
11–13, 15–19	Input/Output	I/O ₀ -I/O ₇ . Data lines. Used as input or output lines depending on operation
27	Input/Control	WE. When selected LOW, a WRITE is conducted. When selected HIGH, a READ is conducted
20	Input/Control	CE. When LOW, selects the chip. When HIGH, deselects the chip
22	Input/Control	OE. Output Enable. Controls the direction of the I/O pins. When LOW, the I/O pins behave as outputs. When deasserted HIGH, I/O pins are Tri-stated, and act as input data pins
14	Ground	GND. Ground for the device
28	Power Supply	V _{CC} . Power supply for the device

Note:

^{2.} Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at V_{CC} = V_{CC(typ.)}, T_A = 25°C, and t_{AA} = 70 ns.



Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.) Storage Temperature-65°C to +150°C Ambient Temperature with Power Applied......–55°C to +125°C Supply Voltage to Ground Potential DC Voltage Applied to Outputs in High-Z State $^{[3]}$ –0.5V to $\rm V_{CC}$ + 0.5V DC Input Voltage^[3].....-0.5V to V_{CC} + 0.5V

Output Current into Outputs (LOW)	20 mA
Static Discharge Voltage(per MIL-STD-883, Method 3015)	> 2001V
Latch-up Current	> 200 mA

Operating Range

Device	Range	Ambient Temperature (T _A) ^[4]	V _{CC}
CY62256V	Commercial	0°C to +70°C	2.7V to 3.6V
	Industrial	–40°C to +85°C	
	Automotive	−40°C to +125°C	

Electrical Characteristics Over the Operating Range

				C	62256V	-70	
Parameter	Description	Test Conditions			Typ. ^[2]	Max.	Unit
V _{OH}	Output HIGH Voltage	$I_{OH} = -1.0 \text{ mA}$	V _{CC} = 2.7V	2.4			V
V _{OL}	Output LOW Voltage	I _{OL} = 2.1 mA	V _{CC} = 2.7V			0.4	V
V _{IH}	Input HIGH Voltage			2.2		V _{CC} +0.3V	V
V _{IL}	Input LOW Voltage			-0.5		0.8	V
I _{IX}	Input Leakage Current	$GND \le V_{IN} \le V_{CC}$	Com'l, Ind'l	-1		+1	μА
			Automotive	-10		+10	μА
I _{OZ}	Output Leakage Current	$GND \le V_{IN} \le V_{CC}$, Output Disabled	Com'l, Ind'l	-1		+1	μА
			Automotive	-10		+10	μА
I _{CC}	V _{CC} Operating Supply Current	$V_{CC} = 3.6V, I_{OUT} = 0 \text{ mA},$ $f = f_{Max} = 1/t_{RC}$	All ranges		11	30	mA
I _{SB1}	Automatic CE Power-down Current— TTL Inputs	$V_{CC} = 3.6V, \overline{CE} \ge V_{IH},$ $V_{IN} \ge V_{IH} \text{ or } V_{IN} \le V_{IL}, f = f_{Max}$	All ranges		100	300	μΑ
I _{SB2}	Automatic CE Power-down	$V_{CC} = 3.6V, \overline{CE} \ge V_{CC} - 0.3V$	Com'l		0.1	5	μА
	Current— CMOS Inputs	$V_{IN} \ge V_{CC} - 0.3V \text{ or } V_{IN} \le 0.3V, f = 0$	Ind'l		0.1	10	
			Automotive		0.1	130	

Notes:

^{3.} $V_{\rm IL}$ (min.) = -2.0V for pulse durations of less than 20 ns. 4. $T_{\rm A}$ is the "Instant-On" case temperature.



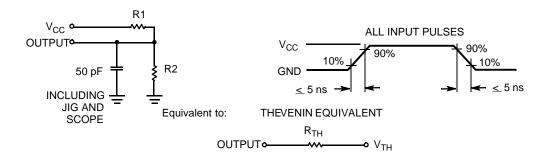
Capacitance^[5]

Parameter	Description	Test Conditions	Max.	Unit
C _{IN}	Input Capacitance	$T_A = 25$ °C, $f = 1$ MHz, $V_{CC} = V_{CC(typ.)}$	6	pF
C _{OUT}	Output Capacitance		8	pF

Thermal Resistance

Parameter	Description	Test Conditions	SOIC	TSOPI	RTSOPI	Unit
Θ_{JA}		Still Air, soldered on a 3 x 4.5 inch, 2-layer printed circuit board	68.45	87.62	87.62	°C/W
Θ _{JC}	Thermal Resistance (Junction to Case) ^[5]		26.94	23.73	23.73	°C/W

AC Test Loads and Waveforms

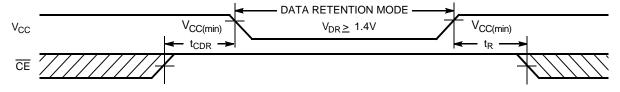


Parameter	3.3V	Units
R1	1100	Ohms
R2	1500	Ohms
R _{TH}	645	Ohms
V _{TH}	1.750	Volts

Data Retention Characteristics (Over the Operating Range)

Parameter	Description	Conditions ^[6]		Min.	Typ. ^[2]	Max.	Unit
V_{DR}	V _{CC} for Data Retention			1.4			V
I _{CCDR}	Data Retention Current	$V_{CC} = 1.4V, \overline{CE} \ge V_{CC} - 0.3V,$ $V_{IN} \ge V_{CC} - 0.3V$ or $V_{IN} \le 0.3V$			0.1	3	μΑ
		$V_{\text{IN}} \ge V_{\text{CC}} - 0.3V \text{ or } V_{\text{IN}} \le 0.3V$	Ind'I		0.1	6	
			Auto		0.1	50	
t _{CDR} ^[6]	Chip Deselect to Data Retention Time			0			ns
t _R ^[6]	Operation Recovery Time			t _{RC}			ns

Data Retention Waveform



Notes:

- 5. Tested initially and after any design or process changes that may affect these parameters.
- 6. No input may exceed V_{CC} + 0.3V.



Switching Characteristics Over the Operating Range^[7]

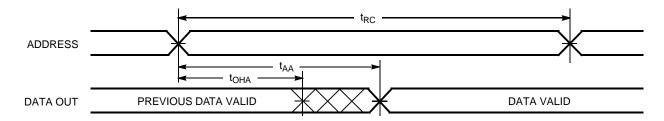
		CY622	CY62256V-70	
Parameter	Description	Min.	Unit	
Read Cycle			•	
t _{RC}	Read Cycle Time	70		ns
t _{AA}	Address to Data Valid		70	ns
t _{OHA}	Data Hold from Address Change	10		ns
t _{ACE}	CE LOW to Data Valid		70	ns
t _{DOE}	OE LOW to Data Valid		35	ns
t _{LZOE}	OE LOW to Low-Z ^[8]	5		ns
t _{HZOE}	OE HIGH to High-Z ^[8, 9]		25	ns
t _{LZCE}	CE LOW to Low-Z ^[8]	10		ns
t _{HZCE}	CE HIGH to High-Z ^[8, 9]		25	ns
t _{PU}	CE LOW to Power-up	0		ns
t _{PD}	CE HIGH to Power-down		70	ns
Write Cycle ^[10, 11]			•	
t_{WC}	Write Cycle Time	70		ns
t _{SCE}	CE LOW to Write End	60		ns
t _{AW}	Address Set-up to Write End	60		ns
t _{HA}	Address Hold from Write End	0		ns
t _{SA}	Address Set-up to Write Start	0		ns
t _{PWE}	WE Pulse Width	50		ns
t _{SD}	Data Set-up to Write End	30		ns
t_{HD}	Data Hold from Write End	0		ns
t _{HZWE}	WE LOW to High-Z ^[8, 9]		25	
t _{LZWE}	WE HIGH to Low-Z ^[8]	10		ns

<sup>Notes:
7. Test conditions assume signal transition time of 5 ns or less timing reference levels of V_{CC}/2, input pulse levels of 0 to V_{CC}, and output loading of the specified l_{OL}/l_{OH} and 50 pF load capacitance.
8. At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE}, t_{HZOE} is less than t_{LZOE}, and t_{HZWE} for any given device.
9. t_{HZOE}, t_{HZCE}, and t_{HZWE} are specified with C_L = 5 pF as in (b) of AC Test Loads. Transition is measured ± 200 mV from steady-state voltage.
10. The internal write time of the memory is defined by the overlap of CE LOW and WE LOW. Both signals must be LOW to initiate a write and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.
11. The minimum write cycle time for write cycle #3 (WE controlled, OE LOW) is the sum of t_{HZWE} and t_{SD}.</sup>

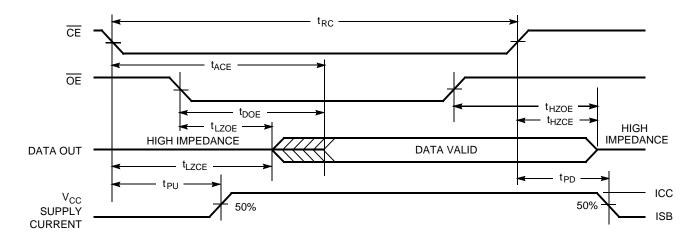


Switching Waveforms

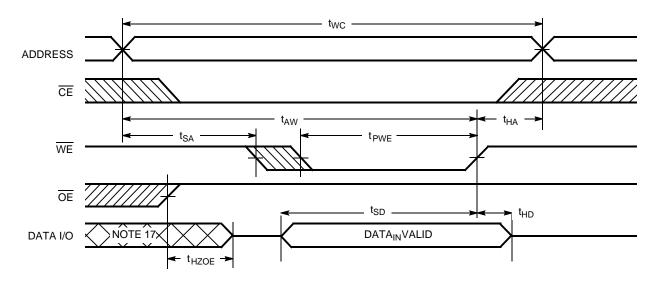
Read Cycle No. 1 (Address Transition Controlled)^[12, 13]



Read Cycle No. 2 (OE Controlled)[13, 14]



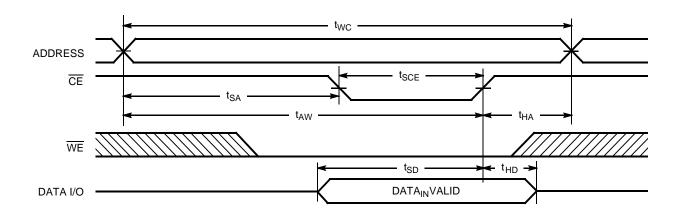
Write Cycle No. 1 (WE Controlled)[10, 15, 16]



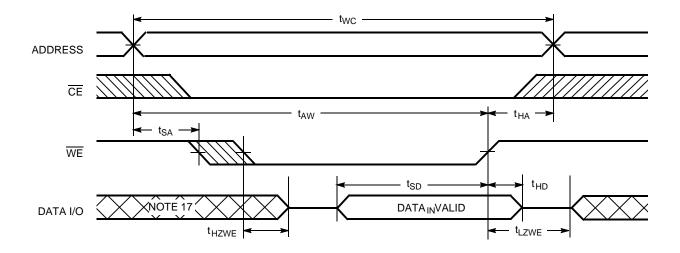
- Notes:
 12. <u>Dev</u>ice is continuously selected. <u>OE</u>, <u>CE</u> = V_{IL}.
 13. <u>WE</u> is HIGH for read cycle.
- 14. Address valid prior to or coincident with $\overline{\text{CE}}$ transition LOW.
- 15. Data I/O is high impedance if $\overline{OE} = V_{|H:}$ 16. If \overline{CE} goes HIGH simultaneously with WE HIGH, the output remains in a high-impedance state.
- 17. During this period, the I/Os are in output state and input signals should not be applied.



Switching Waveforms (continued) Write Cycle No. 2 ($\overline{\text{CE}}$ Controlled) $^{[10,\ 15,\ 16]}$

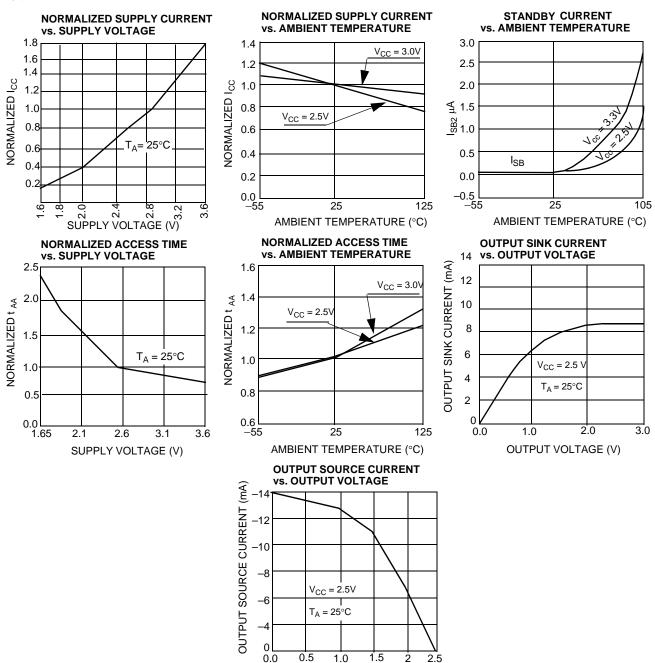


Write Cycle No. 3 (WE Controlled, OE LOW)[11, 16]





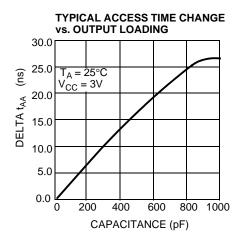
Typical DC and AC Characteristics

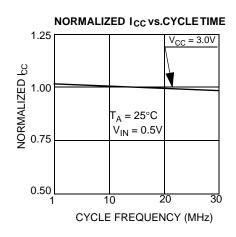


OUTPUT VOLTAGE (V)



Typical DC and AC Characteristics (continued)





Truth Table

CE	WE	OE	Inputs/Outputs	Mode	Power
Н	X	Х	High-Z	Deselect/Power-down	Standby (I _{SB})
L	Н	L	Data Out	Read	Active (I _{CC})
L	L	Х	Data In	Write	Active (I _{CC})
L	Н	Н	High-Z	Deselect, Output Disabled	Active (I _{CC})

Ordering Information

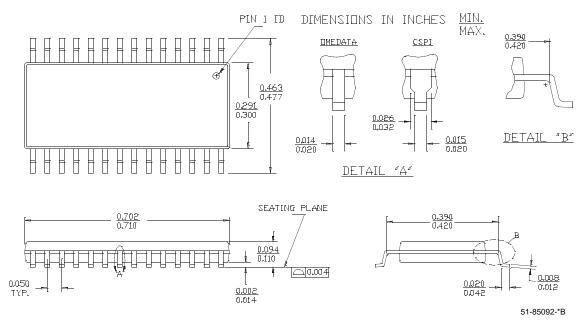
Speed (ns)	Ordering Code	Package Diagram	Package Type	Operating Range
70	70 CY62256VLL-70SNC		28-pin (300-mil Narrow Body) SNC	Commercial
	CY62256VLL-70SNXC		28-pin (300-mil Narrow Body) SNC (Pb-Free)	
	CY62256VLL-70ZC	51-85071	28-pin TSOP I	
	CY62256VLL-70ZXC		28-pin TSOP I (Pb-Free)	
	CY62256VLL-70SNXI	51-85092	28-pin (300-mil Narrow Body) SNC (Pb-Free)	Industrial
	CY62256VLL-70ZI	51-85071	28-pin TSOP I	
	CY62256VLL-70ZXI		28-pin TSOP I (Pb-Free)	
	CY62256VLL-70ZRI	51-85074	28-pin Reverse TSOP I	
	CY62256VLL-70ZRXI		28-pin Reverse TSOP I (Pb-Free)	
	CY62256VLL-70SNE	51-85092	28-pin (300-mil Narrow Body) SNC	Automotive
	CY62256VLL-70SNXE		28-pin (300-mil Narrow Body) SNC (Pb-Free)	
	CY62256VLL-70ZE	51-85071	28-pin TSOP I	
	CY62256VLL-70ZXE		28-pin TSOP I (Pb-Free)	
	CY62256VLL-70ZRE	51-85074	28-pin Reverse TSOP I	
	CY62256VLL-70ZRXE		28-pin Reverse TSOP I (Pb-Free)	

Please contact your local Cypress sales representative for availability of these parts



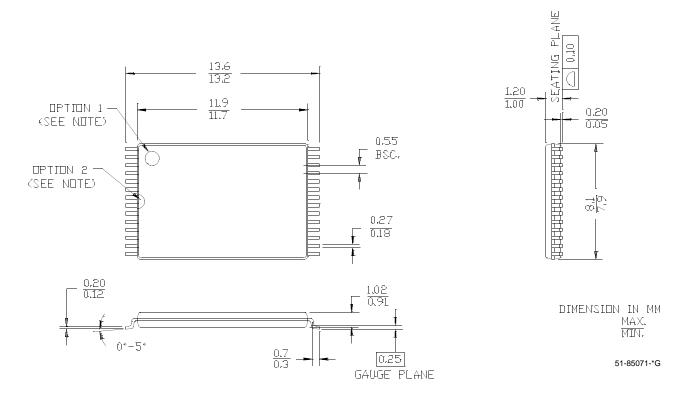
Package Diagrams

28-pin (300-mil) SNC (Narrow Body) (51-85092)



28-pin Thin Small Outline Package Type 1 (8 x 13.4 mm) (51-85071)

NOTE: ORIENTATION I.D MAY BE LOCATED EITHER AS SHOWN IN OPTION 1 OR OPTION 2

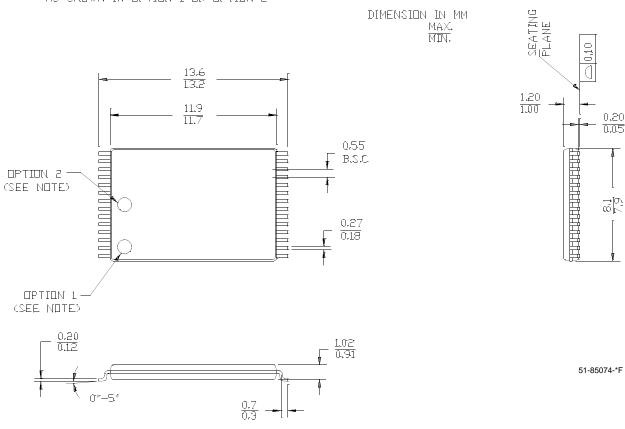




Package Diagrams (continued)

28-pin Reverse Thin Small Outline Package Type 1 (8 x 13.4 mm) (51-85074)

NOTE: ORIENTATION ID MAY BE LOCATED EITHER AS SHOWN IN OPTION 1 OR OPTION 2



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Document History Page

REV.	ECN NO.	Issue Date	Orig. of Change	Description of Change
**	107248	09/10/01	SZV	Changed from spec number: 38-00519 to 38-05057
*A	111445	11/01/01	MGN	Removed obsolete parts. Change to standard format
*B	115229	05/23/02	GBI	Changed SN package diagram
*C	116507	09/04/02	GBI	Added footnote 1 Clarified I _{CC} spec for V _{CC(typ)} = 2.5V
*D	239134	See ECN	AJU	Added Automotive product information
*E	344595	See ECN	SYT	Added Pb-Free packages on page# 10
*F	493277	See ECN	VKN	Changed address of Cypress Semiconductor Corporation on Page# 1 from "3901 North First Street" to "198 Champion Court" Removed part # CY62256V25LL from the product offering Updated Ordering Information Table